

Multifunctional Manual Wire Bonder

Model: SA-MMWB-450PW

SA-MMWB-450PW is a multifunctional manual wire bonder. It delivers stable ultrasonic output with closed-loop force control and electric-driven design requiring no compressed air. It supports tailless bumping and deep-access bonding, and adapts well to soft substrates for microwave components, lasers, optical communications, sensors, MEMS and power devices.



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SA-MMWB-450PW

Feature

- High precision close loop force control (Accuracy within 1g)
- High stability of bond point
- One key switch frequency
- Drive by electricity without compressed air
- Unique tailless bumping process and super adaptability for soft substrates
- Bond head designed by parallelogram support large module of deep access

Application

- Microwave components
- Lasers
- Optical communication devices
- Sensors
- MEMS
- RF modules
- SAW devices
- Power devices
- Discrete devices

Specifications:

Parameter	Descriptions
Bonding Wire Type	Al(18~100μm),Au(15~75μm), Gold Ribbon(12.7 × 50μm~25.4 × 300μm),Specific alloy wire
Cavity Depth	21mm(max.)
Capillary Length	19mm/25mm
Spool Diameter	1/2inch(standard),2inches(optional)
Bonding Force	1~250g
Bond Power	Numerical control,1000x subdivision
Clamping Table	Maximum Temperature 200℃
Bond Head Z Range	18mm
Bond Head X-Y Range	X=15mm,Y=15mm
Lifting Table Z Range	0~18mm
Lifting Table X-Y Range	250mm×270mm
Weight	47kg(GW.),70kg(NW.)
Input Voltage	220V±10%@50~60Hz
Power Consumption	≤500W
Size(L×W×H)	640mm×620mm×450mm



Main Features

- ◆ High precision close loop force control (Accuracy within 1g)
- ◆ High stability of bond point
- ◆ One key switch frequency
- ◆ Drive by electricity without compressed air
- ◆ Unique tailless bumping process and super adaptability for soft substrates
- ◆ Bond head designed by parallelogram support large module of deep access

Specification

- ◆ Application : Discrete, Microwave Module, Laser, Optical Communication Devices, Sensors, MEMS, SAW, RF Components, Power Device, etc.
- ◆ Bond Wire : Al(18~ 100 μ m), Au(15~75 μ m), Gold Ribbon(12.7x50 μ m~25.4x300 μ m), Specific alloy wire.
- ◆ Device Depth : Max:21mm
- ◆ Spool : 1/2 inch or 2 inch
- ◆ Bond Head Z Range : 19mm
- ◆ Bond Head X-Y Range : X=15mm, Y= 15mm
- ◆ Lifting Table Z Range : 0~19mm
- ◆ Lifting Table X-Y Range : 268mmx273mm
- ◆ Bond Power : Numerical control, 1000x subdivision
- ◆ Bond Force : 0~250g
- ◆ Type of Bonding Tools : 25mm/19mm
- ◆ Clamping Table : Maximum Temperature 200 $^{\circ}$ C
- ◆ Weight : About 47kg